

Patent Abstracts of Japan

PUBLICATION NUMBER : 05102522  
PUBLICATION DATE : 23-04-93

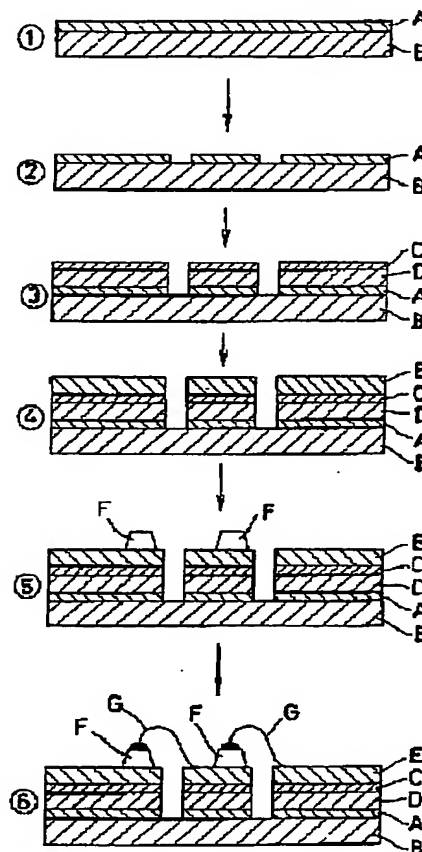
APPLICATION DATE : 09-05-91  
APPLICATION NUMBER : 03132185

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INT.CL. : H01L 33/00

TITLE : MANUFACTURE OF LED DISPLAY DEVICE



ABSTRACT : PURPOSE: To enable adjusting the thickness of an Au film, and control metallized sheet resistance in a low range, by forming an Ni.P film and an Au film on ITO by electroless plating.

CONSTITUTION: A transparent conducting film ITOA is formed on a glass substrate B by sputter evaporation or vacuum evaporation, and patterned in a specified pattern by a photolithography process. An Ni.P film D is formed only on the ITOA by an electroless plating method, and then an Au film C is substituted for the upper layer of the Ni.P film D by a substitution plating method. By an electroplating method, an Au film E is formed on a formed metallized film. By an electroless plating method and an electroplating method, an Ni.P film D is formed on the ITOA. At the same time, an LED chip F is die-bonded on a specified position of the formed metallized film where the Au films C and E are formed, by using Ag paste or the like. Finally the LED chip E is wire-bonded to a bonding pad and the Au film E by using Au wires G.

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